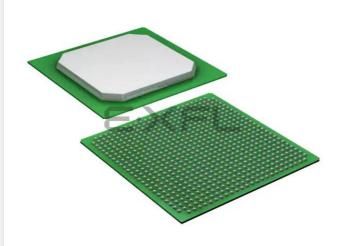
Intel - EP4CGX75DF27I7 Datasheet





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Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Details	
Product Status	Active
Number of LABs/CLBs	4620
Number of Logic Elements/Cells	73920
Total RAM Bits	4257792
Number of I/O	310
Number of Gates	-
Voltage - Supply	1.16V ~ 1.24V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	672-BGA
Supplier Device Package	672-FBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep4cgx75df27i7

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

A DC signal is equivalent to 100% duty cycle. For example, a signal that overshoots to 4.3 V can only be at 4.3 V for 65% over the lifetime of the device; for a device lifetime of 10 years, this amounts to 65/10ths of a year.

Symbol	Parameter	Condition (V)	Overshoot Duration as % of High Time	Unit
		V ₁ = 4.20	100	%
		V ₁ = 4.25	98	%
		$V_1 = 4.30$	65	%
		V ₁ = 4.35	43	%
Vi	AC Input Voltage	$V_1 = 4.40$	29	%
	Voltago	$V_1 = 4.45$	20	%
		$V_1 = 4.50$	13	%
		V ₁ = 4.55	9	%
		$V_1 = 4.60$	6	%

Table 1–2. Maximum Allowed Overshoot During Transitions over a 10-Year Time Frame for Cyclone IV Devices

Figure 1–1 shows the methodology to determine the overshoot duration. The overshoot voltage is shown in red and is present on the input pin of the Cyclone IV device at over 4.3 V but below 4.4 V. From Table 1–2, for an overshoot of 4.3 V, the percentage of high time for the overshoot can be as high as 65% over a 10-year period. Percentage of high time is calculated as ([delta T]/T) × 100. This 10-year period assumes that the device is always turned on with 100% I/O toggle rate and 50% duty cycle signal. For lower I/O toggle rates and situations in which the device is in an idle state, lifetimes are increased.



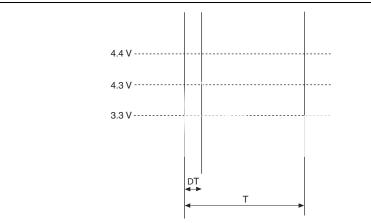


Table 1–3.	Recommended Operating Conditions for Cyclone IV E Devices ^{(1), (2}	⁹ (Part 2 of 2)
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Symbol	Parameter	Conditions	Min	Тур	Max	Unit
I _{Diode}	Magnitude of DC current across PCI-clamp diode when enable	_	_		10	mA

Notes to Table 1–3:

 Cyclone IV E 1.0 V core voltage devices only support C8L, C9L, and I8L speed grades. Cyclone IV E 1.2 V core voltage devices only support C6, C7, C8, I7, and A7 speed grades.

(2) V_{CCI0} for all I/O banks must be powered up during device operation. All vCCA pins must be powered to 2.5 V (even when PLLs are not used) and must be powered up and powered down at the same time.

(3) V_{CC} must rise monotonically.

(4) V_{CCI0} powers all input buffers.

(5) The POR time for Standard POR ranges between 50 and 200 ms. Each individual power supply must reach the recommended operating range within 50 ms.

(6) The POR time for Fast POR ranges between 3 and 9 ms. Each individual power supply must reach the recommended operating range within 3 ms.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V _{ccint} <i>(3)</i>	Core voltage, PCIe hard IP block, and transceiver PCS power supply		1.16	1.2	1.24	V
V _{CCA} (1), (3)	PLL analog power supply	_	2.375	2.5	2.625	V
V _{CCD_PLL} <i>(2)</i>	PLL digital power supply	_	1.16	1.2	1.24	V
	I/O banks power supply for 3.3-V operation	—	3.135	3.3	3.465	V
V _{CCINT} (3) V _{CCA} (1), (3)	I/O banks power supply for 3.0-V operation	—	2.85	3	3.15	V
\ <i>I</i> (3). (4)	I/O banks power supply for 2.5-V operation	lock, and ly 1.16 1.2 1.24 2.375 2.5 2.625 1.16 1.2 1.24 3.3-V 3.135 3.3 3.465 3.0-V 2.85 3 3.15 2.5-V 2.375 2.5 2.625 1.8-V 2.85 3 3.15 2.5-V 2.375 2.5 2.625 1.8-V 1.71 1.8 1.89 1.5-V 1.425 1.5 1.575 1.2-V 1.425 1.5 1.575 1.2-V 1.14 1.2 1.26 power 2.85 3 3.15 power 2.375 2.5 2.625 power 1.71 1.8 1.89 power 1.71 1.8 1.89 power <td< td=""><td>V</td></td<>	V			
VCCIO (S), (S)	I/O banks power supply for 1.8-V operation	—	1.71	1.8	1.89	V
	I/O banks power supply for 1.5-V operation	—	1.425	1.5	2.625 1.24 3.465 3.15 2.625 1.89 1.575 3.465 3.15 2.625 1.89 1.575 1.26	V
	I/O banks power supply for 1.2-V operation	_	1.14	1.2	1.26	V
	Differential clock input pins power supply for 3.3-V operation	—	3.135	3.3	3.465	V
	Curr (a)Core voltage, PCIe hard IP block, and transceiver PCS power supply—1.16(1). (a)PLL analog power supply—2.375D_PLL (2)PLL digital power supply for 3.3-V—1.161/O banks power supply for 3.3-V—3.1351/O banks power supply for 3.0-V—2.851/O banks power supply for 2.5-V—2.3751/O banks power supply for 1.8-V—1.711/O banks power supply for 1.8-V—1.711/O banks power supply for 1.2-V—1.4251/O banks power supply for 1.2-V—1.141/O banks power supply for 3.0-V operation—2.851/O banks power supply for 1.2-V—1.141/O banks power supply for 1.2-V—1.141/O banks power supply for 3.0-V operation—2.3751/O banks power supply for 1.2-V—1.141/O banks power supply for 1.2-V—1.141/O banks power supply for 3.0-V operation—2.3751/O banks power supply for 3.0-V operation—1.141/O banks power supply for 3.0-V operation—2.3751/O banks power supply for 3.0-V operation—1.711/O banks power supply for 2.5-V operation—1.711/I banks power supply for 3.0-V operation—1.711/I banks power supply for 1.2-V operation—1.711/I banks power supply for 1.2-V operation—1.711/I banks power supply for 1.2-V operation—1.4251/I	3	3.15	V		
V _{CC CLKIN}		—	2.375	2.5	2.625	V
(3), (5), (6)		—	1.71	1.8	1.24 2.625 1.24 3.465 3.15 2.625 1.89 1.575 3.465 3.465 1.89 1.575 1.26 3.465 3.15 2.625 1.89 1.575 1.26 1.89 1.575 1.26	V
		—	1.425	375 2.5 2.625 .16 1.2 1.24 135 3.3 3.465 .85 3 3.15 .85 2.5 2.625 .71 1.8 1.89 .425 1.5 1.575 .14 1.2 1.26 .85 3 3.15 .71 1.8 1.89 .14 1.2 1.26 .135 3.3 3.465 .85 3 3.15 .14 1.2 1.26 .135 3.3 3.465 .85 3 3.15 .85 3 3.15 .85 3 3.15 .71 1.8 1.89 .425 1.5 1.575 .14 1.2 1.26	V	
V _{CCD_PLL} (2) V _{CCIO} (3), (4) V _{CC_CLKIN} (3), (5), (6)		—	1.14	1.2	1.26	V
V _{CCH_GXB}	Transceiver output buffer power supply	_	2.375	2.5	2.625	V

Table 1–4. Recommended Operating Conditions for Cyclone IV GX Devices (Part 1 of 2)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V _{CCA_GXB}	Transceiver PMA and auxiliary power supply	_	2.375	2.5	2.625	V
V _{CCL_GXB}	Transceiver PMA and auxiliary power supply	_	1.16	1.2	1.24	V
VI	DC input voltage	—	-0.5		3.6	V
V ₀	DC output voltage	—	0	—	V _{CCIO}	V
т	Operating junction temperature	For commercial use	0	—	85	°C
TJ	Operating junction temperature	For industrial use	-40		100	°C
t _{RAMP}	Power supply ramp time	Standard power-on reset (POR) ⁽⁷⁾	50 µs	_	50 ms	_
		Fast POR ⁽⁸⁾	50 µs		3 ms	_
I _{Diode}	Magnitude of DC current across PCI-clamp diode when enabled	_	_	_	10	mA

Table 1-4. Recommended Operating Conditions for Cyclone IV GX Devices (Part 2 of 2)

Notes to Table 1-4:

- (1) All VCCA pins must be powered to 2.5 V (even when PLLs are not used) and must be powered up and powered down at the same time.
- (2) You must connect $V_{CCD PLL}$ to V_{CCINT} through a decoupling capacitor and ferrite bead.
- (3) Power supplies must rise monotonically.
- (4) V_{CCI0} for all I/O banks must be powered up during device operation. Configurations pins are powered up by V_{CCI0} of I/O Banks 3, 8, and 9 where I/O Banks 3 and 9 only support V_{CCI0} of 1.5, 1.8, 2.5, 3.0, and 3.3 V. For fast passive parallel (FPP) configuration mode, the V_{CCI0} level of I/O Bank 8 must be powered up to 1.5, 1.8, 2.5, 3.0, and 3.3 V.
- (5) You must set $V_{CC_{CLKIN}}$ to 2.5 V if you use CLKIN as a high-speed serial interface (HSSI) refclk or as a DIFFCLK input.
- (6) The CLKIN pins in I/O Banks 3B and 8B can support single-ended I/O standard when the pins are used to clock left PLLs in non-transceiver applications.
- (7) The POR time for Standard POR ranges between 50 and 200 ms. V_{CCINT}, V_{CCA}, and V_{CCIO} of I/O Banks 3, 8, and 9 must reach the recommended operating range within 50 ms.
- (8) The POR time for Fast POR ranges between 3 and 9 ms. V_{CCINT}, V_{CCA}, and V_{CCIO} of I/O Banks 3, 8, and 9 must reach the recommended operating range within 3 ms.

ESD Performance

This section lists the electrostatic discharge (ESD) voltages using the human body model (HBM) and charged device model (CDM) for Cyclone IV devices general purpose I/Os (GPIOs) and high-speed serial interface (HSSI) I/Os. Table 1–5 lists the ESD for Cyclone IV devices GPIOs and HSSI I/Os.

Table 1–5. ESD for Cyclone IV Devices GPIOs and HSSI I/0
--

Symbol	Parameter	Passing Voltage	Unit
M	ESD voltage using the HBM (GPIOs) ⁽¹⁾	± 2000	V
VESDHBM		V	
V	ESD using the CDM (GPIOs)	± 500	V
VESDCDM	ESD using the CDM (HSSI I/Os) ⁽²⁾	± 250	V

Notes to Table 1-5:

(1) The passing voltage for EP4CGX15 and EP4CGX30 row I/Os is ±1000V.

(2) This value is applicable only to Cyclone IV GX devices.

Internal Weak Pull-Up and Weak Pull-Down Resistor

Table 1–12 lists the weak pull-up and pull-down resistor values for Cyclone IV devices.

Table 1–12. Internal Weak Pull-Up and Weak Pull-Down Resistor Values for Cyclone IV Devices ⁽¹⁾

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
		$V_{CCIO} = 3.3 \text{ V} \pm 5\%$ (2), (3)	7	25	41	kΩ
R_PU Value of the I/O pin pull-up resistor before and during configuration, as well as user mode if you enable the programmable pull-up resistor option	Value of the I/O nin null-un resistor	$V_{CCIO} = 3.0 \text{ V} \pm 5\%$ (2), (3)	7	28	47	kΩ
	$V_{CCIO} = 2.5 \text{ V} \pm 5\%$ (2), (3)	8	35	61	kΩ	
	, , , , , , , , , , , , , , , , , , ,	$V_{CCIO} = 1.8 \text{ V} \pm 5\%$ (2), (3)	10	57	108	kΩ
	programmable puil-up resistor option	$V_{CCIO} = 1.5 \text{ V} \pm 5\%$ (2), (3)	13	82	163	kΩ
		$V_{CCIO} = 1.2 \text{ V} \pm 5\%$ (2), (3)	19	143	351	kΩ
		$V_{CCIO} = 3.3 \text{ V} \pm 5\%$ (4)	6	19	30	kΩ
		$V_{CCIO} = 3.0 \text{ V} \pm 5\%$ (4)	6	22	36	kΩ
R_{PD}	Value of the I/O pin pull-down resistor before and during configuration	$V_{CCIO} = 2.5 \text{ V} \pm 5\%$ (4)	6	25	43	kΩ
		$V_{CCIO} = 1.8 \text{ V} \pm 5\%$ (4)	7	35	71	kΩ
		$V_{CCIO} = 1.5 V \pm 5\%$ (4)	8	50	112	kΩ

Notes to Table 1–12:

- (1) All I/O pins have an option to enable weak pull-up except the configuration, test, and JTAG pins. The weak pull-down feature is only available for JTAG TCK.
- (2) Pin pull-up resistance values may be lower if an external source drives the pin higher than V_{CCIO} .
- $\begin{array}{ll} \text{(3)} & \text{R}_{_{PU}} = (\text{V}_{\text{CCI0}} \text{V}_{\text{I}})/\text{I}_{\text{R}_{_{PU}}} \\ & \text{Minimum condition: } -40^{\circ}\text{C}; \ \text{V}_{\text{CCI0}} = \text{V}_{\text{CC}} + 5\%, \ \text{V}_{\text{I}} = \text{V}_{\text{CC}} + 5\% 50 \ \text{mV}; \\ & \text{Typical condition: } 25^{\circ}\text{C}; \ \text{V}_{\text{CCI0}} = \text{V}_{\text{CC}}, \ \text{V}_{\text{I}} = 0 \ \text{V}; \\ & \text{Maximum condition: } 100^{\circ}\text{C}; \ \text{V}_{\text{CCI0}} = \text{V}_{\text{CC}} 5\%, \ \text{V}_{\text{I}} = 0 \ \text{V}; \\ & \text{Maximum condition: } 100^{\circ}\text{C}; \ \text{V}_{\text{CCI0}} = \text{V}_{\text{CC}} 5\%, \ \text{V}_{\text{I}} = 0 \ \text{V}; \\ & \text{maximum condition: } 100^{\circ}\text{C}; \ \text{V}_{\text{CO}} = \text{V}_{\text{CC}} 5\%, \ \text{V}_{\text{I}} = 0 \ \text{V}; \\ & \text{Maximum condition: } 100^{\circ}\text{C}; \ \text{V}_{\text{CO}} = \text{V}_{\text{CC}} 5\%, \ \text{V}_{\text{I}} = 0 \ \text{V}; \\ & \text{Maximum condition: } 100^{\circ}\text{C}; \ \text{V}_{\text{CO}} = \text{V}_{\text{CO}} 5\%, \ \text{V}_{\text{I}} = 0 \ \text{V}; \\ & \text{Maximum condition: } 100^{\circ}\text{C}; \ \text{V}_{\text{CO}} = \text{V}_{\text{CO}} 5\%, \ \text{V}_{\text{I}} = 0 \ \text{V}; \\ & \text{Maximum condition: } 100^{\circ}\text{C}; \ \text{V}_{\text{CO}} = \text{V}_{\text{CO}} 5\%, \ \text{V}_{\text{I}} = 0 \ \text{V}; \\ & \text{Maximum condition: } 100^{\circ}\text{C}; \ \text{V}_{\text{CO}} = \text{V}_{\text{CO}} 5\%, \ \text{V}_{\text{I}} = 0 \ \text{V}; \\ & \text{Maximum condition: } 100^{\circ}\text{C}; \ \text{V}_{\text{CO}} = \text{V}_{\text{CO}} 5\%, \ \text{V}_{\text{I}} = 0 \ \text{V}; \\ & \text{Maximum condition: } 100^{\circ}\text{C}; \ \text{V}_{\text{CO}} = 10^{\circ}\text{C}; \ \text{V}_{\text{CO}} = 10^{\circ$
- $\begin{array}{ll} (4) & R_{_PD} = V_I/I_{R_PD} \\ & \text{Minimum condition:} -40^{\circ}\text{C}; \ V_{CCIO} = V_{CC} + 5\%, \ V_I = 50 \ \text{mV}; \\ & \text{Typical condition:} \ 25^{\circ}\text{C}; \ V_{CCIO} = V_{CC}, \ V_I = V_{CC} 5\%; \\ & \text{Maximum condition:} \ 100^{\circ}\text{C}; \ V_{CCIO} = V_{CC} 5\%, \ V_I = V_{CC} 5\%; \ \text{in which } V_I \ \text{refers to the input voltage at the I/O pin.} \end{array}$

Hot-Socketing

Table 1–13 lists the hot-socketing specifications for Cyclone IV devices.

Table 1–13. Hot-Socketing Specifications for Cyclone IV Devices

Symbol	Parameter	Maximum
I _{IOPIN(DC)}	DC current per I/O pin	300 μA
I _{IOPIN(AC)}	AC current per I/O pin	8 mA <i>(1)</i>
I _{XCVRTX(DC)}	DC current per transceiver TX pin	100 mA
I _{XCVRRX(DC)}	DC current per transceiver RX pin	50 mA

Note to Table 1-13:

(1) The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns, |IIOPIN| = C dv/dt, in which C is the I/O pin capacitance and dv/dt is the slew rate.

During hot-socketing, the I/O pin capacitance is less than 15 pF and the clock pin capacitance is less than 20 pF.

Transceiver Performance Specifications

Table 1–21 lists the Cyclone IV GX transceiver specifications.

Table 1–21. Transceiver Specification for Cyclone IV GX Devices (Part 1 of 4)

Symbol/	0 and 111 and		C6		C7, 17			C8			
Description	Conditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
Reference Clock						-		<u>.</u>		<u>.</u>	-
Supported I/O Standards		1.2 V F	PCML, 1.5	V PCML, 3	.3 V PCN	1L, Differe	ntial LVPE	CL, LVD	S, HCSL		
Input frequency from REFCLK input pins	_	50	_	156.25	50	_	156.25	50	_	156.25	MHz
Spread-spectrum modulating clock frequency	Physical interface for PCI Express (PIPE) mode	30	_	33	30	_	33	30	_	33	kHz
Spread-spectrum downspread	PIPE mode	_	0 to 0.5%	_	_	0 to -0.5%	_	_	0 to 0.5%	_	_
Peak-to-peak differential input voltage	_	0.1	_	1.6	0.1	_	1.6	0.1	_	1.6	V
V_{ICM} (AC coupled)	—		1100 ± 5	%		1100 ± 59	%		1100 ± 5	%	mV
V_{ICM} (DC coupled)	HCSL I/O standard for PCIe reference clock	250	_	550	250	_	550	250	_	550	mV
Transmitter REFCLK Phase Noise ⁽¹⁾	Frequency offset		_	-123	_	_	-123	_	_	-123	dBc/Hz
Transmitter REFCLK Total Jitter ⁽¹⁾	= 1 MHz – 8 MHZ		_	42.3	_	_	42.3	_	_	42.3	ps
R _{ref}			2000 ± 1%		_	2000 ± 1%	_	_	2000 ± 1%	_	Ω
Transceiver Clock											
cal_blk_clk clock frequency	_	10	_	125	10	_	125	10	_	125	MHz
fixedclk clock frequency	PCIe Receiver Detect	_	125	_	_	125	_	_	125	—	MHz
reconfig_clk clock frequency	Dynamic reconfiguration clock frequency	2.5/ 37.5 <i>(2)</i>	_	50	2.5/ 37.5 <i>(2)</i>	_	50	2.5/ 37.5 <i>(2)</i>	_	50	MHz
Delta time between reconfig_clk	_	_	_	2	_	_	2	_	_	2	ms
Transceiver block minimum power-down pulse width	_	_	1		_	1	_	_	1	—	μs

Symbol/	Ocaditions	C6 C7, I7 C8				11					
Description	Conditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
Receiver					•	•		•	•		
Supported I/O Standards	1.4 V PCML, 1.5 V PCML, 2.5 V PCML, LVPECL, LVDS										
Data rate (F324 and smaller package) ⁽¹⁵⁾	_	600	_	2500	600	_	2500	600	_	2500	Mbps
Data rate (F484 and larger package) ⁽¹⁵⁾	—	600	_	3125	600	_	3125	600	_	2500	Mbps
Absolute V _{MAX} for a receiver pin <i>(3)</i>	—	_	_	1.6	_	_	1.6	_	_	1.6	V
Operational V _{MAX} for a receiver pin	—	_	_	1.5	_	_	1.5	_	_	1.5	V
Absolute V _{MIN} for a receiver pin	_	-0.4	_	_	-0.4	_	_	-0.4	_	_	V
Peak-to-peak differential input voltage V _{ID} (diff p-p)	V _{ICM} = 0.82 V setting, Data Rate = 600 Mbps to 3.125 Gbps	0.1	_	2.7	0.1	_	2.7	0.1	_	2.7	V
V _{ICM}	V _{ICM} = 0.82 V setting	_	820 ± 10%	_	_	820 ± 10%	_	_	820 ± 10%	_	mV
Differential on-chip	100– Ω setting		100	—	_	100		_	100	—	Ω
termination resistors	150– Ω setting	—	150	_	_	150		_	150	—	Ω
Differential and common mode return loss	PIPE, Serial Rapid I/O SR, SATA, CPRI LV, SDI, XAUI					Compliant	Ľ				_
Programmable ppm detector ⁽⁴⁾	—				± 62.5	, 100, 128 250, 300					ppm
Clock data recovery (CDR) ppm tolerance (without spread-spectrum clocking enabled)				±300 <i>(5)</i> , ±350 <i>(6)</i> , <i>(7)</i>			±300 (5), ±350 (6), (7)		_	±300 (5), ±350 (6), (7)	ppm
CDR ppm tolerance (with synchronous spread-spectrum clocking enabled) ⁽⁸⁾	_	_		350 to 5350 (7), (9)	_		350 to 5350 (7), (9)	_		350 to 5350 (7), (9)	ppm
Run length	—		80		—	80	_	—	80		UI
	No Equalization		_	1.5	—	_	1.5	—	_	1.5	dB
Programmable	Medium Low		_	4.5	_	_	4.5	_		4.5	dB
equalization	Medium High		_	5.5	—	_	5.5	—	_	5.5	dB
	High	—		7	-	_	7	-	_	7	dB

Table 1–21.	Transceiver S	necification fo	r Cyclone	IV GX Devices	(Part 2 of 4)
	Inalisourior o	poontioution to		11 UN DU11003	(1 41 (2 01 4)

Table 1–21. Transceiver Specification for Cyclone IV GX Devices (Part 4 of 4)

Symbol/	Conditions		C6			C7, 17				Unit	
Description	Conultions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	UIIIL
PLD-Transceiver Inte	rface										
Interface speed (F324 and smaller package)	_	25	_	125	25	_	125	25	_	125	MHz
Interface speed (F484 and larger package)	_	25	_	156.25	25	_	156.25	25	_	156.25	MHz
Digital reset pulse width	_		•	•	Minimu	m is 2 pa	rallel clock	cycles	•		

Notes to Table 1–21:

(1) This specification is valid for transmitter output jitter specification with a maximum total jitter value of 112 ps, typically for 3.125 Gbps SRIO and XAUI protocols.

(2) The minimum reconfig_clk frequency is 2.5 MHz if the transceiver channel is configured in **Transmitter Only** mode. The minimum reconfig_clk frequency is 37.5 MHz if the transceiver channel is configured in **Receiver Only** or **Receiver and Transmitter** mode.

- (3) The device cannot tolerate prolonged operation at this absolute maximum.
- (4) The rate matcher supports only up to ±300 parts per million (ppm).
- (5) Supported for the F169 and F324 device packages only.
- (6) Supported for the F484, F672, and F896 device packages only. Pending device characterization.
- (7) To support CDR ppm tolerance greater than ±300 ppm, implement ppm detector in user logic and configure CDR to Manual Lock Mode.
- (8) Asynchronous spread-spectrum clocking is not supported.
- (9) For the EP4CGX30 (F484 package only), EP4CGX50, and EP4CGX75 devices, the CDR ppl tolerance is ±200 ppm.
- (10) Time taken until pll_locked goes high after pll_powerdown deasserts.
- (11) Time that the CDR must be kept in lock-to-reference mode after rx_analogreset deasserts and before rx_locktodata is asserted in manual mode.

(12) Time taken to recover valid data after the rx_locktodata signal is asserted in manual mode (Figure 1–2), or after rx_freqlocked signal goes high in automatic mode (Figure 1–3).

(13) Time taken to recover valid data after the rx_locktodata signal is asserted in manual mode.

- (14) Time taken to recover valid data after the $rx_freqlocked$ signal goes high in automatic mode.
- (15) To support data rates lower than the minimum specification through oversampling, use the CDR in LTR mode only.

Figure 1–2 shows the lock time parameters in manual mode.

LTD = lock-to-data. LTR = lock-to-reference.

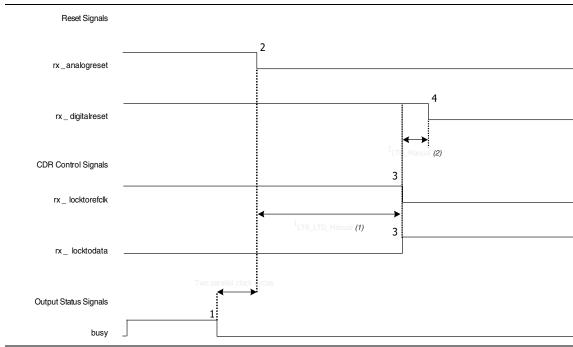


Figure 1–2. Lock Time Parameters for Manual Mode

Figure 1–3 shows the lock time parameters in automatic mode.

Figure 1–3. Lock Time Parameters for Automatic Mode

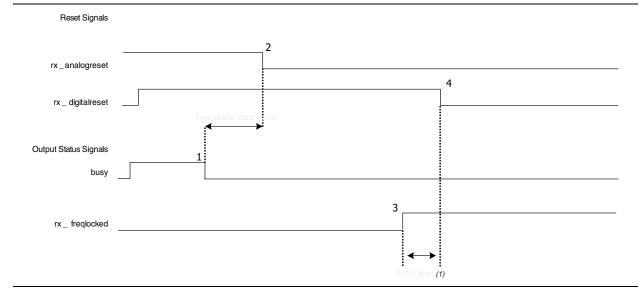


Table 1–23 lists the Cyclone IV GX transceiver block AC specifications.

Symbol/	0		C6			C7, 17	7		C 8		Unit
Description	Conditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
PCIe Transmit Jitter Gene	ration ⁽³⁾	-		<u>.</u>	-		<u>.</u>			<u>.</u>	
Total jitter at 2.5 Gbps (Gen1)	Compliance pattern	_	_	0.25	_	_	0.25	_	_	0.25	UI
PCIe Receiver Jitter Toler	ance ⁽³⁾	•						•	•		•
Total jitter at 2.5 Gbps (Gen1)	Compliance pattern		> 0.6	6		> 0.6	;		> 0.6	;	UI
GIGE Transmit Jitter Gene	ration ⁽⁴⁾	•						•			•
Deterministic jitter	Pattern = CRPAT			0.14			0.14			0.14	UI
(peak-to-peak)	Falleni = UNFAI			0.14		_	0.14	_	_	0.14	01
Total jitter (peak-to-peak)	Pattern = CRPAT	—		0.279	_		0.279	_		0.279	UI
GIGE Receiver Jitter Toler	ance ⁽⁴⁾										
Deterministic jitter tolerance (peak-to-peak)	Pattern = CJPAT		> 0.4	ļ		> 0.4				UI	
Combined deterministic and random jitter tolerance (peak-to-peak)	Pattern = CJPAT	> 0.66				> 0.66	6		6	UI	

Table 1–23. Transceiver Block AC Specification for Cyclone IV GX Devices (1), (2)

Notes to Table 1-23:

(1) Dedicated refclk pins were used to drive the input reference clocks.

(2) The jitter numbers specified are valid for the stated conditions only.

(3) The jitter numbers for PIPE are compliant to the PCIe Base Specification 2.0.

(4) The jitter numbers for GIGE are compliant to the IEEE802.3-2002 Specification.

Core Performance Specifications

The following sections describe the clock tree specifications, PLLs, embedded multiplier, memory block, and configuration specifications for Cyclone IV Devices.

Clock Tree Specifications

Table 1–24 lists the clock tree specifications for Cyclone IV devices.

 Table 1–24. Clock Tree Performance for Cyclone IV Devices (Part 1 of 2)

Device	Performance													
Device	C6	C7	C8	C8L ⁽¹⁾	C9L ⁽¹⁾	17	18L ⁽¹⁾	A7	Unit					
EP4CE6	500	437.5	402	362	265	437.5	362	402	MHz					
EP4CE10	500	437.5	402	362	265	437.5	362	402	MHz					
EP4CE15	500	437.5	402	362	265	437.5	362	402	MHz					
EP4CE22	500	437.5	402	362	265	437.5	362	402	MHz					
EP4CE30	500	437.5	402	362	265	437.5	362	402	MHz					
EP4CE40	500	437.5	402	362	265	437.5	362	402	MHz					

Embedded Multiplier Specifications

Table 1–26 lists the embedded multiplier specifications for Cyclone IV devices.

Table 1–26. Embedded Multiplier Specifications for Cyclone IV Devices

Mode	Resources Used		I	Performance)		Unit
Mode	Number of Multipliers	C6	C7, I7, A7	C8	C8L, 18L	C9L	Unit
9 × 9-bit multiplier	1	340	300	260	240	175	MHz
18 × 18-bit multiplier	1	287	250	200	185	135	MHz

Memory Block Specifications

Table 1–27 lists the M9K memory block specifications for Cyclone IV devices.

Table 1–27. Memory Block Performance Specifications for Cyclone IV Devices

		Resou	rces Used		Per	forman	ce		
Memory	Mode	LEs	M9K Memory	C6	C7, I7, A7	C8	C8L, 18L	C9L	Unit
	FIFO 256 × 36	47	1	315	274	238	200	157	MHz
M9K Block	Single-port 256 × 36	0	1	315	274	238	200	157	MHz
WISK DIUCK	Simple dual-port 256 × 36 CLK	0	1	315	274	238	200	157	MHz
	True dual port 512 × 18 single CLK	0	1	315	274	238	200	157	MHz

Configuration and JTAG Specifications

Table 1–28 lists the configuration mode specifications for Cyclone IV devices.

Table 1–28. Passive Configuration Mode Specifications for Cyclone IV Devices (1)

Programming Mode	V _{CCINT} Voltage Level (V)	DCLK f _{max}	Unit
Passive Serial (PS)	1.0 <i>(3</i>)	66	MHz
rassive Sellai (rS)	1.2	133	MHz
East Dagaina Darallal (EDD) (2)	1.0 <i>(3)</i>	66	MHz
Fast Passive Parallel (FPP) ⁽²⁾	1.2 (4)	100	MHz

Notes to Table 1-28:

- (1) For more information about PS and FPP configuration timing parameters, refer to the *Configuration and Remote System Upgrades in Cyclone IV Devices* chapter.
- (2) FPP configuration mode supports all Cyclone IV E devices (except for E144 package devices) and EP4CGX50, EP4CGX75, EP4CGX110, and EP4CGX150 only.
- (3) V_{CCINT} = 1.0 V is only supported for Cyclone IV E 1.0 V core voltage devices.
- (4) Cyclone IV E devices support 1.2 V V_{CCINT}. Cyclone IV E 1.2 V core voltage devices support 133 MHz DCLK f_{MAX} for EP4CE6, EP4CE10, EP4CE15, EP4CE22, EP4CE30, and EP4CE40 only.

- ***** For more information about the supported maximum clock rate, device and pin planning, IP implementation, and device termination, refer to *Section III: System Performance Specifications* of the *External Memory Interfaces Handbook*.
- Actual achievable frequency depends on design- and system-specific factors. Perform HSPICE/IBIS simulations based on your specific design and system setup to determine the maximum achievable frequency in your system.

High-Speed I/O Specifications

Table 1–31 through Table 1–36 list the high-speed I/O timing for Cyclone IV devices. For definitions of high-speed timing specifications, refer to "Glossary" on page 1–37.

Table 1–31. RSDS Transmitter Timing Specifications for Cyclone IV Devices (1), (2), (4) (Part 1 of 2)

0 milest			C6			C7, I	7		C8, A	7		C8L, I	8L		C9L		
Symbol	Modes	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
	×10	5		180	5		155.5	5		155.5	5		155.5	5	—	132.5	MHz
	×8	5		180	5		155.5	5		155.5	5		155.5	5		132.5	MHz
f _{HSCLK} (input clock	×7	5	_	180	5	—	155.5	5	_	155.5	5	_	155.5	5	_	132.5	MHz
(input clock frequency)	×4	5	_	180	5	—	155.5	5	_	155.5	5	_	155.5	5	_	132.5	MHz
1 37	×2	5		180	5		155.5	5		155.5	5		155.5	5		132.5	MHz
	×1	5	_	360	5		311	5	_	311	5	_	311	5		265	MHz
	×10	100	_	360	100		311	100	_	311	100	_	311	100	_	265	Mbps
	×8	80		360	80		311	80		311	80		311	80		265	Mbps
Device operation in	×7	70		360	70	—	311	70		311	70		311	70	—	265	Mbps
Mbps	×4	40		360	40	—	311	40		311	40		311	40	—	265	Mbps
	×2	20	_	360	20		311	20	_	311	20	_	311	20	—	265	Mbps
	×1	10		360	10	—	311	10		311	10		311	10	—	265	Mbps
t _{DUTY}	—	45		55	45		55	45		55	45		55	45		55	%
Transmitter channel-to- channel skew (TCCS)	_	_		200	_	_	200	_	_	200	_		200	_	_	200	ps
Output jitter (peak to peak)	—	_	_	500	_	_	500	_	_	550	_	_	600	_	_	700	ps
t _{RISE}	20 - 80%, C _{LOAD} = 5 pF	_	500	_	_	500	_	_	500	_	_	500		_	500		ps
t _{FALL}	20 – 80%, C _{LOAD} = 5 pF	_	500	_	_	500	_	_	500	_	_	500	_	_	500		ps

Symbol	Modes		C6		C7, I7			C8, A7			C8L, I8L			C9L			Unit
Symbol	WOUCS	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	UIIIL
t _{LOCK} (3)				1	—	—	1	—	_	1		—	1			1	ms

Table 1–31. RSDS Transmitter Timing Specifications for Cyclone IV Devices ^{(1), (2), (4)} (Part 2 of 2)

Notes to Table 1-31:

(1) Applicable for true RSDS and emulated RSDS_E_3R transmitter.

(2) Cyclone IV E devices—true RSDS transmitter is only supported at the output pin of Row I/O Banks 1, 2, 5, and 6. Emulated RSDS transmitter is supported at the output pin of all I/O Banks. Cyclone IV GX devices—true RSDS transmitter is only supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is only supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is only supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is only supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is only supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is only supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is only supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is only supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is only supported at the

pin of I/O Banks 3, 4, 5, 6, 7, 8, and 9.
(3) t_{LOCK} is the time required for the PLL to lock from the end-of-device configuration.

(4) Cyclone IV E 1.0 V core voltage devices only support C8L, C9L, and I8L speed grades. Cyclone IV E 1.2 V core voltage devices only support C6, C7, C8, I7, and A7 speed grades. Cyclone IV GX devices only support C6, C7, C8, and I7 speed grades.

Gumbal	Madas		C6			C7, 17	,		C8, A7	7	(C8L, 18	SL		C9L		Unit
Symbol	Modes	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	UNIT
	×10	5	—	85	5	—	85	5		85	5		85	5	—	72.5	MHz
	×8	5		85	5		85	5	-	85	5	_	85	5	—	72.5	MHz
f _{HSCLK} (input clock	×7	5	—	85	5	_	85	5	_	85	5	_	85	5	—	72.5	MHz
frequency)	×4	5		85	5		85	5	_	85	5	_	85	5	—	72.5	MHz
,	×2	5	_	85	5	_	85	5		85	5		85	5	_	72.5	MHz
	×1	5	_	170	5	_	170	5	_	170	5	_	170	5	—	145	MHz
	×10	100		170	100		170	100	_	170	100	_	170	100	—	145	Mbps
	×8	80	_	170	80		170	80	_	170	80	_	170	80	—	145	Mbps
Device operation in	×7	70	_	170	70		170	70	_	170	70	_	170	70	—	145	Mbps
Mbps	×4	40	—	170	40	_	170	40	_	170	40	_	170	40	—	145	Mbps
	×2	20	_	170	20		170	20	_	170	20	_	170	20	—	145	Mbps
	×1	10	_	170	10	_	170	10	_	170	10	_	170	10	—	145	Mbps
t _{DUTY}	—	45	_	55	45	-	55	45	_	55	45	_	55	45	—	55	%
TCCS	—	—	_	200	_		200	_	_	200	_	_	200	_	—	200	ps
Output jitter (peak to peak)	_	_	_	500	_	_	500	_	_	550	_	_	600	_		700	ps
	20-80%,																
t _{RISE}	C _{LOAD} = 5 pF	-	500		_	500		_	500		_	500		_	500	—	ps
t _{FALL}	20 - 80%, C _{LOAD} =	_	500	_	_	500	_	_	500	_	_	500	_	_	500		ps
	5 pF																

Table 1–32. Emulated RSDS_E_1R Transmitter Timing Specifications for Cyclone IV Devices ^{(1), (3)} (Part 1 of 2)

Symbol	Modes		C6			C7, 17			C8, A7	7		C8L, 18	L		C9L		Unit
əyiinui	WIUUES	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
t _{LOCK} (2)	_	—		1		—	1	_		1			1		—	1	ms

Table 1–32. Emulated RSDS_E	1R Transmitter Timing	Specifications for C	vclone IV Devices ^{(1), (3)}	(Part 2 of 2)
		• • • • • • • • • • • • • • • • •		(

Notes to Table 1-32:

(1) Emulated RSDS_E_1R transmitter is supported at the output pin of all I/O Banks of Cyclone IV E devices and I/O Banks 3, 4, 5, 6, 7, 8, and 9 of Cyclone IV GX devices.

(2) t_{LOCK} is the time required for the PLL to lock from the end-of-device configuration.

(3) Cyclone IV E 1.0 V core voltage devices only support C8L, C9L, and I8L speed grades. Cyclone IV E 1.2 V core voltage devices only support C6, C7, C8, I7, and A7 speed grades. Cyclone IV GX devices only support C6, C7, C8, and I7 speed grades.

Gumbal	Symbol Modes		C6			C7, 17	7		C8, A	7		C8L, I	8L		C9L		Unit
Symbol	woues	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	UIIIL
	×10	5	_	200	5	—	155.5	5	—	155.5	5	_	155.5	5	_	132.5	MHz
	×8	5	_	200	5	—	155.5	5	—	155.5	5	_	155.5	5	_	132.5	MHz
f _{HSCLK} (input clock	×7	5	_	200	5	_	155.5	5	—	155.5	5	_	155.5	5	_	132.5	
frequency)	×4	5	_	200	5	—	155.5	5	—	155.5	5		155.5	5		132.5	MHz
,	×2	5	_	200	5	_	155.5	5	—	155.5	5	_	155.5	5	_	132.5	MHz
	×1	5	_	400	5	_	311	5	—	311	5	_	311	5	_	265	MHz
	×10	100	_	400	100	_	311	100	—	311	100		311	100		265	Mbps
	×8	80	_	400	80	_	311	80	—	311	80	_	311	80	_	265	5 Mbps
Device operation in	×7	70	_	- 400 70 — 311 70 — 311 70 — 311 70 — 311 70	70	—	265	Mbps									
Mbps	×4	40	—	400	40	—	311	40	—	311	40	_	311	40	—	265	Mbps
	×2	20		400	20		311	20	_	311	20		311	20	_	265	Mbps
	×1	10	_	400	10	—	311	10		311	10	_	311	10		265	Mbps
t _{DUTY}	—	45	_	55	45	_	55	45	—	55	45		55	45		55	%
TCCS	—	_	_	200	_	_	200	_	—	200	_	_	200	_	_	200	ps
Output jitter (peak to peak)	—	_	_	500	_	_	500	_		550	_	_	600		_	700	ps
t _{RISE}	20 - 80%, C _{LOAD} = 5 pF	_	500	_	_	500	_	_	500	_	_	500	_	_	500	_	ps
t _{FALL}	20 - 80%, C _{LOAD} = 5 pF	_	500	_	_	500	_	_	500	_	_	500	_	_	500	_	ps
t _{LOCK} (3)				1			1			1			1			1	ms

Table 1–33. Mini-LVDS Transmitter Timing Specifications for Cyclone IV Devices (1), (2), (4)

Notes to Table 1-33:

(1) Applicable for true and emulated mini-LVDS transmitter.

(2) Cyclone IV E—true mini-LVDS transmitter is only supported at the output pin of Row I/O Banks 1, 2, 5, and 6. Emulated mini-LVDS transmitter is supported at the output pin of all I/O banks.
Cyclone IV GY—true mini-LVDS transmitter is only supported at the output pin of Row I/O Banks 5 and 6. Emulated mini-LVDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated mini-LVDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated mini-LVDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated mini-LVDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated mini-LVDS transmitter is supported at the output pin of Row I/O Banks 5.

Cyclone IV GX—true mini-LVDS transmitter is only supported at the output pin of Row I/O Banks 5 and 6. Emulated mini-LVDS transmitter is supported at the output pin of I/O Banks 3, 4, 5, 6, 7, 8, and 9.

(3) t_{LOCK} is the time required for the PLL to lock from the end-of-device configuration.

(4) Cyclone IV E 1.0 V core voltage devices only support C8L, C9L, and I8L speed grades. Cyclone IV E 1.2 V core voltage devices only support C6, C7, C8, I7, and A7 speed grades. Cyclone IV GX devices only support C6, C7, C8, and I7 speed grades.

Symbol	Madaa	C	6	C7,	, 17	C8,	A7	C8L,	, 18L	C	9L	Unit	
Symbol	Symbol	Modes	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Unit
t _{DUTY}	—	45	55	45	55	45	55	45	55	45	55	%	
TCCS	—	_	200	—	200	_	200	_	200	—	200	ps	
Output jitter (peak to peak)	_		500	_	500	_	550	_	600	_	700	ps	
t _{LOCK} (2)	_		1	_	1		1		1	_	1	ms	

Table 1–35. Emulated LVDS Transmitter Timing Specifications for Cyclone IV Devices ^{(1), (3)} (Part 2 of 2)

Notes to Table 1-35:

(1) Cyclone IV E—emulated LVDS transmitter is supported at the output pin of all I/O Banks.

Cyclone IV GX—emulated LVDS transmitter is supported at the output pin of I/O Banks 3, 4, 5, 6, 7, 8, and 9.

(2) t_{LOCK} is the time required for the PLL to lock from the end-of-device configuration.

(3) Cyclone IV E 1.0 V core voltage devices only support C8L, C9L, and I8L speed grades. Cyclone IV E 1.2 V core voltage devices only support C6, C7, C8, I7, and A7 speed grades. Cyclone IV GX devices only support C6, C7, C8, and I7 speed grades.

Gumbal	Madaa	C	6	C7,	, 17	C8,	A7	C8L	, 18L	C)L	11:4
Symbol	Modes	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Unit
	×10	10	437.5	10	370	10	320	10	320	10	250	MHz
	×8	10	437.5	10	370	10	320	10	320	10	250	MHz
f _{HSCLK} (input	×7	10	437.5	10	370	10	320	10	320	10	250	MHz
clock frequency)	×4	10	437.5	10	370	10	320	10	320	10	250	MHz
, ,,	×2	10	437.5	10	370	10	320	10	320	10	250	MHz
	×1	10	437.5	10	402.5	10	402.5	10	362	10	265	MHz
	×10	100	875	100	740	100	640	100	640	100	500	Mbps
	×8	80	875	80	740	80	640	80	640	80	500	Mbps
HSIODR	×7	70	875	70	740	70	640	70	640	70	500	Mbps
HOIDDN	×4	40	875	40	740	40	640	40	640	40	500	Mbps
	×2	20	875	20	740	20	640	20	640	20	500	Mbps
	×1	10	437.5	10	402.5	10	402.5	10	362	10	265	Mbps
SW	—	_	400	_	400	_	400	_	550	—	640	ps
Input jitter tolerance	_	_	500	_	500	_	550	_	600	_	700	ps
t _{LOCK} (2)	—	—	1	_	1	_	1	—	1	—	1	ms

Table 1–36. LVDS Receiver Timing Specifications for Cyclone IV Devices (1), (3)

Notes to Table 1-36:

(1) Cyclone IV E—LVDS receiver is supported at all I/O Banks.

Cyclone IV GX—LVDS receiver is supported at I/O Banks 3, 4, 5, 6, 7, 8, and 9.

(2) t_{LOCK} is the time required for the PLL to lock from the end-of-device configuration.

(3) Cyclone IV E 1.0 V core voltage devices only support C8L, C9L, and I8L speed grades. Cyclone IV E 1.2 V core voltage devices only support C6, C7, C8, I7, and A7 speed grades. Cyclone IV GX devices only support C6, C7, C8, and I7 speed grades.

External Memory Interface Specifications

The external memory interfaces for Cyclone IV devices are auto-calibrating and easy to implement.

• For more information about the supported maximum clock rate, device and pin planning, IP implementation, and device termination, refer to *Section III: System Performance Specifications* of the *External Memory Interface Handbook*.

Table 1–37 lists the memory output clock jitter specifications for Cyclone IV devices.

Table 1–37. Memory Output Clock Jitter Specifications for Cyclone IV Devices (1), (2)

Parameter	Symbol	Min	Max	Unit
Clock period jitter	t _{JIT(per)}	-125	125	ps
Cycle-to-cycle period jitter	t _{JIT(cc)}	-200	200	ps
Duty cycle jitter	t _{JIT(duty)}	-150	150	ps

Notes to Table 1-37:

(1) Memory output clock jitter measurements are for 200 consecutive clock cycles, as specified in the JEDEC DDR2 standard.

(2) The clock jitter specification applies to memory output clock pins generated using DDIO circuits clocked by a PLL output routed on a global clock (GCLK) network.

Duty Cycle Distortion Specifications

Table 1–38 lists the worst case duty cycle distortion for Cyclone IV devices.

Table 1–38. Duty Cycle Distortion on Cyclone IV Devices I/O Pins (1), (2), (3)

Symbol	C	6	C7	, 17	C8, I8	BL, A7	C	9L	Unit
Symbol	Min	Max	Min	Max	Min	Max	Min	Max	UIIIL
Output Duty Cycle	45	55	45	55	45	55	45	55	%

Notes to Table 1-38:

(1) The duty cycle distortion specification applies to clock outputs from the PLLs, global clock tree, and IOE driving the dedicated and general purpose I/O pins.

(2) Cyclone IV devices meet the specified duty cycle distortion at the maximum output toggle rate for each combination of I/O standard and current strength.

(3) Cyclone IV E 1.0 V core voltage devices only support C8L, C9L, and I8L speed grades. Cyclone IV E 1.2 V core voltage devices only support C6, C7, C8, I7, and A7 speed grades. Cyclone IV GX devices only support C6, C7, C8, and I7 speed grades.

OCT Calibration Timing Specification

Table 1–39 lists the duration of calibration for series OCT with calibration at device power-up for Cyclone IV devices.

Table 1–39. Timing Specification for Series OCT with Calibration at Device Power-Up for Cyclone IV Devices $^{(1)}$

Symbol	Description	Maximum	Units	
t _{octcal}	Duration of series OCT with calibration at device power-up	20	μs	

Note to Table 1-39:

(1) OCT calibration takes place after device configuration and before entering user mode.

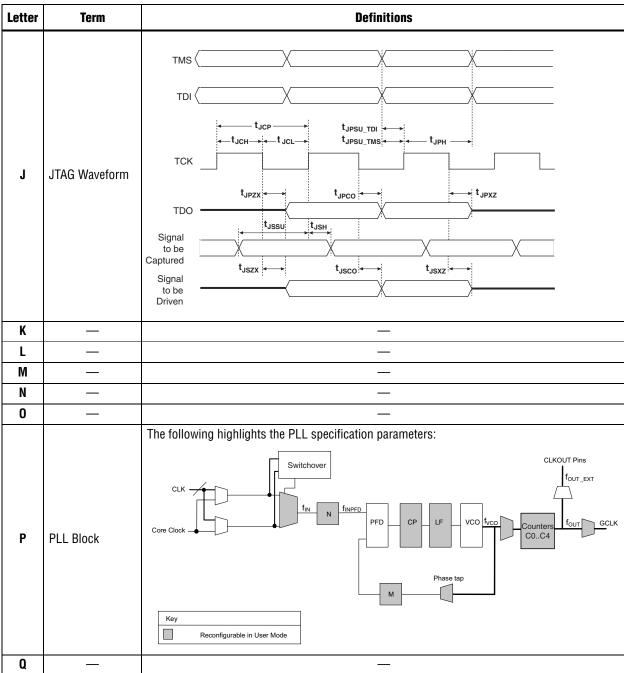


Table 1-46. Glossary (Part 2 of 5)

Table 1-46. Glossary (Part 3 of 5)

Letter	Term	Definitions
	R _L	Receiver differential input discrete resistor (external to Cyclone IV devices).
R	Receiver Input Waveform	Receiver input waveform for LVDS and LVPECL differential standards: Single-Ended Waveform V_{ID} Positive Channel (p) = V_{IH} Negative Channel (n) = V_{IL} Ground Differential Waveform (Mathematical Function of Positive & Negative Channel) V_{ID} V_{ID} V_{ID} V_{ID}
	Receiver input skew margin (RSKM)	High-speed I/O block: The total margin left after accounting for the sampling window and TCCS. RSKM = (TUI – SW – TCCS) / 2.
S	Single-ended voltage- referenced I/O Standard	VCCIO VOH VIH(DC) VIH(DC) VIH(DC) VIL(AC) Vol Vol
	SW (Sampling Window)	High-speed I/O block: The period of time during which the data must be valid to capture it correctly. The setup and hold times determine the ideal strobe position in the sampling window.

Letter	Term	Definitions								
	t _C	High-speed receiver and transmitter input and output clock period.								
	Channel-to- channel-skew (TCCS)	High-speed I/O block: The timing difference between the fastest and slowest output edges, including t_{CO} variation and clock skew. The clock is included in the TCCS measurement.								
	t _{cin}	Delay from the clock pad to the I/O input register.								
	t _{co}	Delay from the clock pad to the I/O output.								
	t _{cout}	Delay from the clock pad to the I/O output register.								
	t _{DUTY}	High-speed I/O block: Duty cycle on high-speed transmitter output clock.								
	t _{FALL}	Signal high-to-low transition time (80–20%).								
	t _H	Input register hold time.								
	Timing Unit Interval (TUI)	High-speed I/O block: The timing budget allowed for skew, propagation delays, and data sampling window. (TUI = $1/(\text{Receiver Input Clock Frequency Multiplication Factor}) = t_C/w)$.								
	t _{INJITTER}	Period jitter on the PLL clock input.								
	t _{outjitter_dedclk}	Period jitter on the dedicated clock output driven by a PLL.								
	t _{outjitter_i0}	Period jitter on the general purpose I/O driven by a PLL.								
	t _{pllcin}	Delay from the PLL inclk pad to the I/O input register.								
т	t _{plicout}	Delay from the PLL inclk pad to the I/O output register.								
	Transmitter Output Waveform	Transmitter output waveforms for the LVDS, mini-LVDS, PPDS and RSDS Differential I/O Standards: Single-Ended Waveform V_{OD} $V_{$								
	t _{RISE}	Signal low-to-high transition time (20–80%).								
	t _{SU}	Input register setup time.								
U	—	_								

Table 1–46. Glossary (Part 4 of 5)

Document Revision History

Table 1–47 lists the revision history for this chapter.

Date	Version	Changes
March 2016	2.0	Updated note (5) in Table 1–21 to remove support for the N148 package.
Ostobor 2014	1.0	Updated maximum value for V _{CCD_PLL} in Table 1–1.
October 2014	1.9	Removed extended temperature note in Table 1–3.
December 2013	1.8	Updated Table 1–21 by adding Note (15).
May 2013	1.7	Updated Table 1–15 by adding Note (4).
		■ Updated the maximum value for V _I , V _{CCD_PLL} , V _{CCI0} , V _{CC_CLKIN} , V _{CCH_GXB} , and V _{CCA_GXB} Table 1–1.
		■ Updated Table 1–11 and Table 1–22.
October 2012	1.6	 Updated Table 1–21 to include peak-to-peak differential input voltage for the Cyclone IV GX transceiver input reference clock.
		■ Updated Table 1–29 to include the typical DCLK value.
		 Updated the minimum f_{HSCLK} value in Table 1–31, Table 1–32, Table 1–33, Table 1–34, and Table 1–35.
		 Updated "Maximum Allowed Overshoot or Undershoot Voltage", "Operating Conditions", and "PLL Specifications" sections.
November 2011	1.5	 Updated Table 1–2, Table 1–3, Table 1–4, Table 1–5, Table 1–8, Table 1–9, Table 1–15, Table 1–18, Table 1–19, and Table 1–21.
		■ Updated Figure 1–1.
		 Updated for the Quartus II software version 10.1 release.
December 2010	1.4	■ Updated Table 1–21 and Table 1–25.
		 Minor text edits.
		Updated for the Quartus II software version 10.0 release:
		■ Updated Table 1–3, Table 1–4, Table 1–21, Table 1–25, Table 1–28, Table 1–30, Table 1–40, Table 1–41, Table 1–42, Table 1–43, Table 1–44, and Table 1–45.
July 2010	1.3	■ Updated Figure 1–2 and Figure 1–3.
		 Removed SW Requirement and TCCS for Cyclone IV Devices tables.
		 Minor text edits.
		Updated to include automotive devices:
		 Updated the "Operating Conditions" and "PLL Specifications" sections.
March 2010	1.2	 Updated Table 1–1, Table 1–8, Table 1–9, Table 1–21, Table 1–26, Table 1–27, Table 1–31, Table 1–32, Table 1–33, Table 1–34, Table 1–35, Table 1–36, Table 1–37, Table 1–38, Table 1–40, Table 1–42, and Table 1–43.
		Added Table 1–5 to include ESD for Cyclone IV devices GPIOs and HSSI I/Os.
		 Added Table 1–44 and Table 1–45 to include IOE programmable delay for Cyclone IV E 1.2 V core voltage devices.
		 Minor text edits.